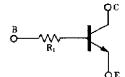


COMPOUND TRANSISTOR BA1A4Z

on-chip resistor PNP silicon epitaxial transistor For mid-speed switching

FEATURES

 On-chip bias resistor (R₁ = 10 kΩ)



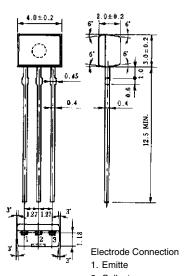
• Complementary transistor with BA1A4Z

ABSOLUTE MAXIMUM RATINGS (Ta = 25°C)

Parameter	Symbol	Ratings	Unit
Collector to base voltage	VcBO	60	V
Collector to emitter voltage	VCEO	50	٧
Emitter to base voltage	VEBO	5	V
Collector current (DC)	Ic(DC)	100	mA
Collector current (Pulse)	Ic(pulse) *	200	mA
Total power dissipation	Рт	250	mW
Junction temperature	Tj	150	°C
Storage temperature	T _{stg}	-55 to +150	°C

^{*} PW \leq 10 ms, duty cycle \leq 50 %

PACKAGE DRAWING (UNIT: mm)



Collector

3. Base

ELECTRICAL CHARACTERISTICS (Ta = 25°C)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Collector cutoff current	Ісво	V _{CB} = 50 V, I _E = 0			100	nA
DC current gain	h _{FE1} **	VcE = 5.0 V, Ic = 5.0 mA	135	340	600	_
DC current gain	hFE2 **	VcE = 5.0 V, Ic = 50 mA	100	300		_
Collector saturation voltage	V _{CE(sat)} **	Ic = 5.0 mA, I _B = 0.25 mA		0.04	0.2	V
High level input voltage	VIL **	VcE = 0.2 V, Ic = 5.0 mA	2.0	0.8		V
Low level input voltage	VIH **	$V_{CE} = 5.0 \text{ V}, \text{ Ic} = 100 \ \mu\text{A}$		0.55	0.5	V
Input resistance	R ₁		0.7	10	13.0	kΩ
Turn-on time	ton	$Vcc = 5.0 \text{ V}, \text{ RL} = 1.0 \text{ k}\Omega$			0.2	μs
Storage time	t stg	V _I = 5.0 V, PW = 2.0 μs			5.0	μs
Turn-off time	toff	duty cycle≤2 %			6.0	μs

^{**} Pulse test PW \leq 350 μ s, duty cycle \leq 2 %

hfe CLASSIFICATION

Marking	Q	Р	К
h _{FE1}	135 to 270	200 to 400	300 to 600

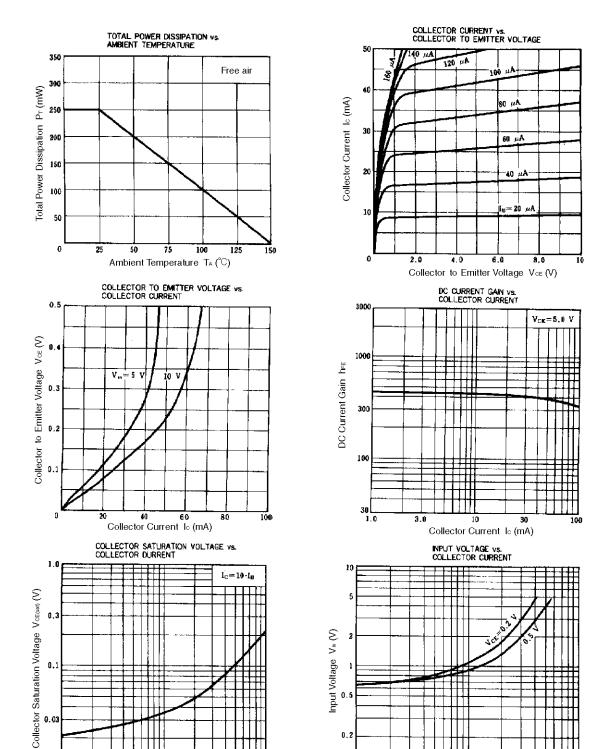
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100

Collector Current lo (mA)



TYPICAL CHARACTERISTICS (Ta = 25°C)



0.01 1.0

3.0

Collector Current lo (mA)

0.2

0.1



[MEMO]

3

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